TopLine®

PRESS RELEASE

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Performance, Reliability of Components in Extreme Environments to Highlight Upcoming MRQW Forum

El Segundo, California, USA – TopLine Corporation's Founder and CEO, Martin Hart, will present a landmark paper, "Solder Column Reliability in Extreme Cold" at The Aerospace Corporation's Microelectronics Reliability and Qualification Workshop (MRQW) in Los Angeles (El Segundo), California on February 10-12, 2026.

This paper documents the findings of the accelerated thermal cycle testing done on TopLine braided columns. The topic addresses column reliability in extremely cold environments. According to Hart, "Braided Solder Columns can withstand the rigors of deep space cold and cryogenic environments and represent a robust new solution to challenges facing next generation large packages in electronics assembly." In the paper, Column Grid Array (CGA) and their performance and reliability in extreme environments are compared, along with different column types. Thermal cycle testing was performed at JPL which is NASA's federally-funded research and development center.

At the MRQW, attendees will engage in discussions related to Technology reliability issues, advanced space microprocessors and memories, Space radiation effects, and more. MRQW provides a forum for discussing issues in all areas of microelectronics reliability and qualification for high-reliability and commercial applications.

About TopLine

TopLine manufactures a wide range of solder columns for CCGA semiconductor packages, and provides Daisy Chain CCGA packages for engineering development, profiling and practice. TopLine products provide hands-on learning for engineers. TopLine is a pioneer in CGA solder columns technology and low temperature cryogenic package-to-board interconnects. To learn more, visit www.CCGA.tv or call (1+) 800 – 776-9888. Email: info@topline.tv.

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